

Kyoung-Sik Moon

List of Publications by Year in descending order

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199
papers

7,366
citations

70961

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58464

82
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199
all docs

199
docs citations

199
times ranked

8815
citing authors

#	ARTICLE	IF	CITATIONS
1	Difluorobenzylamine Treatment of Organolead Halide Perovskite Boosts the High Efficiency and Stability of Photovoltaic Cells. ACS Applied Materials & Interfaces, 2022, 14, 11388-11397.	4.0	11
2	Large-scale production of boron nitride nanosheets-based epoxy nanocomposites with ultrahigh through-plane thermal conductivity for electronic encapsulation. , 2022, , .		2
3	Epoxy Resin with Metal Complex Additives for Improved Reliability of Epoxy-Copper Joint. , 2022, , .		0
4	Comparison of two high temperature treatment methods on preparing electrically conductive polysulfide/Ag composites for aerospace sealant applications. Journal of Applied Polymer Science, 2021, 138, 50121.	1.3	3
5	Atomic Modulation of 3D Conductive Frameworks Boost Performance of MnO ₂ for Coaxial Fiber-Shaped Supercapacitors. Nano-Micro Letters, 2021, 13, 4.	14.4	20
6	Rheological properties and screen printability of UV curable conductive ink for flexible and washable E-textiles. Journal of Materials Science and Technology, 2021, 67, 145-155.	5.6	31
7	Laser-induced nitrogen-self-doped graphite nanofibers from cyanate ester for on-chip micro-supercapacitors. Chemical Engineering Journal, 2021, 404, 126375.	6.6	33
8	Stable high thermal conductivities in BaTiO ₃ ceramic composites utilizing core-shell Ag@BaTiO ₃ particles. Composites Part B: Engineering, 2021, 204, 108496.	5.9	3
9	Nano-conductive Adhesives for Nano-electronics Interconnection. , 2021, , 15-30.		0
10	Some Nanomaterials for Microelectronics and Photonics Packaging. , 2021, , 3-13.		0
11	Melt Processable Novolac Cyanate Ester/Biphenyl Epoxy Copolymer Series with Ultrahigh Glass-Transition Temperature. ACS Applied Materials & Interfaces, 2021, 13, 15551-15562.	4.0	23
12	Excellent high-temperature piezoelectric energy harvesting properties in flexible polyimide/3D PbTiO ₃ flower composites. Nano Energy, 2021, 82, 105778.	8.2	29
13	Investigation of Aromatic Voltage Stabilizers for Enhancing High Voltage Stability of Epoxy for Power Electronics. , 2021, , .		0
14	Large-scale and low-cost production of graphene nanosheets-based epoxy nanocomposites with latent catalyst to enhance thermal conductivity for electronic encapsulation. , 2021, , .		1
15	A novel flower-like architecture comprised of 3D interconnected Co-Al-Ox/Sy decorated lignosulfonate-derived carbon nanosheets for flexible supercapacitors and electrocatalytic water splitting. Carbon, 2021, 184, 386-399.	5.4	24
16	Surface Modification of Backsheets Using Coupling Agents for Roll-To-Roll Processed Thin-Film Solar Photovoltaic (PV) Module Packaging Application. ACS Applied Materials & Interfaces, 2021, 13, 1682-1692.	4.0	4
17	Greatly enhanced power conversion efficiency of hole-transport-layer-free perovskite solar cell with coherent interfaces of perovskite and carbon layers. Nano Energy, 2020, 77, 105110.	8.2	31
18	Synthesis of Boron Nitride Coated Silica Filler for Preparing Thermally Conductive Epoxy Composites. , 2020, , .		0

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19	Enhanced dielectric constant and energy density in a BaTiO ₃ /polymer-matrix composite sponge. <i>Communications Materials</i> , 2020, 1, .	2.9	18
20	Fabrication of stretchable and conductive polymer nanocomposites based on interconnected graphene aerogel. <i>Composites Science and Technology</i> , 2020, 200, 108430.	3.8	14
21	A sustainable reduction route of graphene oxide by industrial waste lignin for versatile applications in energy and environment. <i>Journal of Cleaner Production</i> , 2020, 268, 122019.	4.6	21
22	Flexible and electrically conductive composites based on 3D hierarchical silver dendrites. <i>Soft Matter</i> , 2020, 16, 6765-6772.	1.2	12
23	Hydrothermal synthesis of BaTiO ₃ nanowires for high energy density nanocomposite capacitors. <i>Journal of Materials Science</i> , 2020, 55, 6903-6914.	1.7	19
24	Laser-induced and KOH-activated 3D graphene: A flexible activated electrode fabricated via direct laser writing for in-plane micro-supercapacitors. <i>Chemical Engineering Journal</i> , 2020, 393, 124672.	6.6	93
25	Systematic evaluation of cyanate ester/epoxidized cresol novolac copolymer resin system for high temperature power electronic packaging applications. <i>Polymer</i> , 2020, 195, 122454.	1.8	18
26	RGO-templated lignin-derived porous carbon materials for renewable high-performance supercapacitors. <i>Electrochimica Acta</i> , 2020, 353, 136482.	2.6	32
27	Epoxy/ Triazine Copolymer Resin System for High Temperature Encapsulant Applications. , 2019, , .		4
28	Moisture Barrier, Mechanical, and Thermal Properties of PDMS-PIB Blends for Solar Photovoltaic (PV) Module Encapsulant. , 2019, , .		1
29	Novel Decapsulation Method for Silver-Based Wire-Bond Semiconductor Packages With High Reliability Using Mixed Salt/ Acid Chemistry. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2019, 9, 1459-1465.	1.4	0
30	Microstructures of Pb-Free Solder Joints by Reflow and Thermo-Compression Bonding (TCB) Processes. , 2019, , .		3
31	Reduction of Ag Corrosion Rate During Decapsulation of Ag Wire Bond Packages. , 2019, , .		1
32	Epoxy Composites with Surface Modified Silicon Carbide Filler for High Temperature Molding Compounds. , 2019, , .		3
33	Ultra Low Resistivity and High Electrical Stability Silo-Ag ECAs Produced from Curing Chemistry Optimization for Flexible Electronics. , 2019, , .		0
34	Formulation and Processing of Conductive Polysulfide Sealants for Automotive and Aerospace Applications. , 2019, , .		4
35	A strategy for design of non-percolative composites with stable giant dielectric constants and high energy densities. <i>Nano Energy</i> , 2019, 58, 419-426.	8.2	37
36	Controlled synthesis and evaluation of cyanate ester/epoxy copolymer system for high temperature molding compounds. <i>Journal of Polymer Science Part A</i> , 2018, 56, 1337-1345.	2.5	19

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37	Effect of polymer binders on graphene-based free-standing electrodes for supercapacitors. <i>Electrochimica Acta</i> , 2018, 267, 213-221.	2.6	44
38	Scalable Preparation of Fully Coated Ag@BaTiO ₃ Core@Shell Particles via Poly(vinylpyrrolidone) Assistance for High- <i>k</i> Applications. <i>ACS Applied Nano Materials</i> , 2018, 1, 1396-1405.	2.4	17
39	Processing and characterization of silver-filled conductive polysulfide sealants for aerospace applications. <i>Soft Matter</i> , 2018, 14, 9036-9043.	1.2	16
40	Polyimide incorporated cyanate ester/epoxy copolymers for high-temperature molding compounds. <i>Journal of Polymer Science Part A</i> , 2018, 56, 2412-2421.	2.5	11
41	Cyanate Ester/Epoxy Co-Curing System with Thermal Stabilizers for High Temperature Stability. , 2018, , .		4
42	Design and Surface Modification of PET Substrates Using UV/Ozone Treatment for Roll-to-Roll Processed Solar Photovoltaic (PV) Module Packaging. , 2018, , .		5
43	Stretchable, Printable and Electrically Conductive Composites for Wearable RF Antennas. , 2018, , .		5
44	Ultrafast Molecular Stitching of Graphene Films at the Ethanol/Water Interface for High Volumetric Capacitance. <i>Nano Letters</i> , 2017, 17, 1365-1370.	4.5	42
45	Self-Patterning of Silica/Epoxy Nanocomposite Underfill by Tailored Hydrophilic-Superhydrophobic Surfaces for 3D Integrated Circuit (IC) Stacking. <i>ACS Applied Materials & Interfaces</i> , 2017, 9, 8437-8442.	4.0	13
46	Particle size effect in porous film electrodes of ligand-modified graphene for enhanced supercapacitor performance. <i>Carbon</i> , 2017, 119, 296-304.	5.4	27
47	Microscopic vertical orientation of nano-interspaced graphene architectures in deposit films as electrodes for enhanced supercapacitor performance. <i>Nano Energy</i> , 2017, 32, 88-95.	8.2	23
48	Stretchable and Electrically Conductive Composites Fabricated from Polyurethane and Silver Nano/Microstructures. , 2017, , .		7
49	Design of Miura Folding-Based Micro-Supercapacitors as Foldable and Miniaturized Energy Storage Devices. , 2017, , .		4
50	Systematic study on structural and electronic properties of diamine/triamine functionalized graphene networks for supercapacitor application. <i>Nano Energy</i> , 2017, 31, 183-193.	8.2	124
51	Epoxy/Cyanate Ester Copolymer Material for Molding Compounds in High-Temperature Operations. , 2017, , .		12
52	Toughening Underfills by Stress-Absorbing Core-Shell Fillers. , 2017, , .		0
53	Polysiloxane-Based Surface Modification of Silica Fillers for Low Stress Underfill. , 2016, , .		2
54	Vertically Aligned and Interconnected Graphene Networks for High Thermal Conductivity of Epoxy Composites with Ultralow Loading. <i>Chemistry of Materials</i> , 2016, 28, 6096-6104.	3.2	325

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55	Highly Conductive Polyurethane/Polyaniline-Based Composites for Wearable Electronic Applications. , 2016, , .		7
56	Molecular Level Study of Graphene Networks Functionalized with Phenylenediamine Monomers for Supercapacitor Electrodes. Chemistry of Materials, 2016, 28, 9110-9121.	3.2	98
57	Miniaturized Integrated Micro-Supercapacitors as Efficient Power Sources for Wearable and Biocompatible Electronic Devices. , 2016, , .		4
58	Recent Developments in Design and Fabrication of Graphene-Based Interdigital Micro-Supercapacitors for Miniaturized Energy Storage Devices. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1752-1765.	1.4	21
59	Molecular engineering of aromatic amine spacers for high-performance graphene-based supercapacitors. Nano Energy, 2016, 21, 276-294.	8.2	61
60	Sulfonated polyaniline decorated graphene nanocomposites as supercapacitor electrodes. Materials Letters, 2016, 166, 12-15.	1.3	36
61	Solution-processed flexible solid-state micro-supercapacitors for on-chip energy storage devices. , 2015, , .		6
62	Alternating current line-filter based on electrochemical capacitor utilizing template-patterned graphene. Scientific Reports, 2015, 5, 10983.	1.6	53
63	Conformal Pad-Printing Electrically Conductive Composites onto Thermoplastic Hemispheres: Toward Sustainable Fabrication of 3-Cents Volumetric Electrically Small Antennas. PLoS ONE, 2015, 10, e0136939.	1.1	12
64	Double-Sided Transferred Carbon Nanotube Arrays for Improved Thermal Interface Materials. Journal of Electronic Packaging, Transactions of the ASME, 2015, 137, .	1.2	10
65	Thermo-mechanical Characterization of Metal/Polymer Composite Filaments and Printing Parameter Study for Fused Deposition Modeling in the 3D Printing Process. Journal of Electronic Materials, 2015, 44, 771-777.	1.0	347
66	Water-dispersible graphene/polyaniline composites for flexible micro-supercapacitors with high energy densities. Nano Energy, 2015, 16, 470-478.	8.2	151
67	Capacitance enhancement by electrochemically active benzene derivatives for graphene-based supercapacitors. RSC Advances, 2015, 5, 84113-84118.	1.7	8
68	Three-dimensional graphene-based composite for flexible electronic applications. , 2015, , .		9
69	Triethanolamine functionalized graphene-based composites for high performance supercapacitors. Journal of Materials Chemistry A, 2015, 3, 21789-21796.	5.2	112
70	Mechanistic investigation of the graphene functionalization using p-phenylenediamine and its application for supercapacitors. Nano Energy, 2015, 17, 160-170.	8.2	143
71	Rational Design of a Printable, Highly Conductive Silicone-based Electrically Conductive Adhesive for Stretchable Radio-Frequency Antennas. Advanced Functional Materials, 2015, 25, 464-470.	7.8	109
72	3D porous graphene with ultrahigh surface area for microscale capacitive deionization. Nano Energy, 2015, 11, 711-718.	8.2	161

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73	Capacitive deionization of water coolant using hybrid carbon electrodes for high power electronic applications. , 2014, , .		0
74	Flexible micro-supercapacitor based on in-situ assembled graphene on metal template at room temperature. Nano Energy, 2014, 10, 222-228.	8.2	111
75	Self-patterning, pre-applied underfilling technology for stack-die packaging. , 2014, , .		1
76	Carbon nanotubes inhibit the free-radical cross-linking of siloxane polymers. Journal of Applied Polymer Science, 2014, 131, .	1.3	3
77	Exfoliated hexagonal boron nitride-based polymer nanocomposite with enhanced thermal conductivity for electronic encapsulation. Composites Science and Technology, 2014, 90, 123-128.	3.8	258
78	High Refractive Index and Transparent Nanocomposites as Encapsulant for High Brightness LED Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 1125-1130.	1.4	17
79	Ultra-high refractive index LED encapsulant. , 2014, , .		5
80	The conduction development mechanism of silicone-based electrically conductive adhesives. Journal of Materials Chemistry C, 2013, 1, 4368.	2.7	30
81	A Kinetics Study on Electrical Resistivity Transition of In Situ Polymer Aging Sensors Based on Carbon-Black-Filled Epoxy Conductive Polymeric Composites (CPCs). Journal of Electronic Materials, 2013, 42, 1114-1121.	1.0	3
82	Highly Conductive, Flexible, Polyurethane-Based Adhesives for Flexible and Printed Electronics. Advanced Functional Materials, 2013, 23, 1459-1465.	7.8	148
83	High refractive index and transparency nanocomposites as encapsulant for high brightness LED packaging. , 2013, , .		3
84	Preparation of Water-Based Carbon Nanotube Inks and Application in the Inkjet Printing of Carbon Nanotube Gas Sensors. Journal of Electronic Packaging, Transactions of the ASME, 2013, 135, .	1.2	20
85	The Standardization of Printable Materials and Direct Writing Systems. Journal of Electronic Packaging, Transactions of the ASME, 2013, 135, .	1.2	21
86	Novel surface modification of nanosilica for low stress underfill. , 2013, , .		4
87	Water Vapor Treatment for Decreasing the Adhesion between Vertically Aligned Carbon Nanotubes and the Growth Substrate. Chemical Vapor Deposition, 2013, 19, 224-227.	1.4	2
88	Stretchable/printed RF devices via high-throughput, high-definability soft-lithography fabrication. , 2013, , .		1
89	Enhanced thermal transport of hexagonal boron nitride filled polymer composite by magnetic field-assisted alignment. , 2013, , .		8
90	Polyhedral oligomeric silsesquioxanes (POSS)-filled underfill with excellent high temperature performance. , 2012, , .		4

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91	Robust, novel, and low cost superhydrophobic nanocomposites coating for reliability improvement of microelectronics. , 2012, , .		1
92	ZnO quantum dots-filled encapsulant for LED packaging. , 2012, , .		7
93	Nano filler dispersion in polymer composites for electronic packaging. , 2012, , .		4
94	Thermal Conductivity Enhancement of Epoxy Composites by Interfacial Covalent Bonding for Underfill and Thermal Interfacial Materials in Cu/Low-K Application. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 1571-1579.	1.4	11
95	Single/few-layer boron nitride-based nanocomposites for high thermal conductivity underfills. , 2012, , .		7
96	Large-scale production of two-dimensional nanosheets. Journal of Materials Chemistry, 2012, 22, 13494.	6.7	351
97	Highly Reliable Copper-Based Conductive Adhesives Using an Amine Curing Agent for in Situ Oxidation/Corrosion Prevention. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 25-32.	1.4	14
98	Controlled Growth of Multilayer, Few-Layer, and Single-Layer Graphene on Metal Substrates. Journal of Physical Chemistry C, 2011, 115, 5232-5238.	1.5	119
99	Nanocomposite for low stress underfill. , 2011, , .		2
100	Nano materials for microelectronic and photonic packaging. Frontiers of Optoelectronics in China, 2010, 3, 139-142.	0.2	2
101	Fast Preparation of Printable Highly Conductive Polymer Nanocomposites by Thermal Decomposition of Silver Carboxylate and Sintering of Silver Nanoparticles. ACS Applied Materials & Interfaces, 2010, 2, 2637-2645.	4.0	130
102	Ultrafast, dry microwave synthesis of graphene sheets. Journal of Materials Chemistry, 2010, 20, 4781.	6.7	128
103	Synthesis of High-Quality Vertically Aligned Carbon Nanotubes on Bulk Copper Substrate for Thermal Management. IEEE Transactions on Advanced Packaging, 2010, 33, 370-376.	1.7	54
104	Interfacial Design of Anisotropic Conductive Adhesive Based Interconnects Using Molecular Wires and Understanding of Their Electrical Conduction. IEEE Transactions on Advanced Packaging, 2010, 33, 892-898.	1.7	2
105	Preparation of highly conductive polymer nanocomposites by low temperature sintering of silver nanoparticles. Journal of Materials Chemistry, 2010, 20, 2018.	6.7	150
106	Electrical properties of ACA joints assisted by conjugated molecular wires. , 2009, , .		3
107	New electrically conductive adhesives (ECAs) for flexible interconnect applications. , 2009, , .		5
108	Epoxy/h-BN composites for thermally conductive underfill material. , 2009, , .		17

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109	Thermal conductivity of epoxy/surface functionalized carbon nano materials. , 2009, , .		1
110	Tin/Indium nanobundle formation from aggregation or growth of nanoparticles. Journal of Nanoparticle Research, 2008, 10, 41-46.	0.8	11
111	Tin/silver/copper alloy nanoparticle pastes for low temperature lead-free interconnect applications. , 2008, , .		7
112	Self-Assembled Monolayer-Assisted Chemical Transfer of In Situ Functionalized Carbon Nanotubes. Journal of the American Chemical Society, 2008, 130, 9636-9637.	6.6	48
113	Silver/polymer nanocomposite as a high-k polymer matrix for dielectric composites with improved dielectric performance. Journal of Materials Chemistry, 2008, 18, 4821.	6.7	113
114	High thermal conductive underfill materials for flip-chip application. , 2008, , .		14
115	Surface treatment of MWCNT array and its polymer composites for TIM application. , 2008, , .		1
116	In-situ reduced silver nanoparticles for highly conductive anisotropic conductive films applications. , 2008, , .		0
117	Chemical Transfer of in-situ Functionalized Aligned Carbon Nanotube Structures for Microelectronic Packaging Applications. , 2008, , .		0
118	Review of Recent Advances in Electrically Conductive Adhesive Materials and Technologies in Electronic Packaging. Journal of Adhesion Science and Technology, 2008, 22, 1593-1630.	1.4	149
119	Novel nonconductive adhesives/films with carbon nanotubes for high performance interconnects. , 2008, , .		0
120	Development of transparent and flexible electrically conductive adhesives for microelectronics applications. , 2008, , .		2
121	Low stress and high thermal conductive underfill for cu/low-k application. , 2008, , .		2
122	Low Temperature Carbon Nanotube Film Transfer via Conductive Adhesives. , 2007, , .		7
123	Low temperature carbon nanotube film transfer via conductive polymer composites. Nanotechnology, 2007, 18, 125203.	1.3	43
124	Tin/silver alloy nanoparticles for low temperature lead-free interconnect applications. , 2007, , .		0
125	Assembling Carbon Nanotube Bundles Using Transfer Process for Fine-Pitch Electrical Interconnect Applications. , 2007, , .		8
126	Synthesis and Thermal and Wetting Properties of Tin/Silver Alloy Nanoparticles for Low Melting Point Lead-Free Solders. Chemistry of Materials, 2007, 19, 4482-4485.	3.2	115

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127	Fine-pitch carbon nanotube bundles assembly using CNT transfer for electrical interconnects. , 2007, , .		7
128	Effect of silica on the non-linear electrical property of polymer composites. , 2007, , .		2
129	High-k polymer nanocomposites for gate dielectric applications. , 2007, , .		0
130	Optimization of Epoxy-Barium Titanate Nanocomposites for High Performance Embedded Capacitor Components. IEEE Transactions on Components and Packaging Technologies, 2007, 30, 248-253.	1.4	16
131	Thermal Properties of Tin/Silver Alloy Nanoparticles for Low Temperature Lead-free Interconnect Technology. , 2007, , .		5
132	High-k Polymer Nanocomposites as Gate Dielectrics for Organic Electronics Applications. , 2007, , .		7
133	The preparation of stable metal nanoparticles on carbon nanotubes whose surfaces were modified during production. Carbon, 2007, 45, 655-661.	5.4	80
134	Magnetic Nanocomposite for Potential Ultrahigh Frequency Microelectronic Application. Journal of Electronic Materials, 2007, 36, 593-597.	1.0	13
135	Ferrite Polymer Composite for Improving the Electromagnetic Compatibility of Semiconductor Packaging. Journal of Electronic Materials, 2007, 36, 1711-1718.	1.0	10
136	Synthesis and dielectric properties of novel high-K polymer composites containing in-situ formed silver nanoparticles for embedded capacitor applications. Journal of Materials Chemistry, 2006, 16, 1543.	6.7	254
137	Surface Functionalized Silver Nanoparticles for Ultrahigh Conductive Polymer Composites. Chemistry of Materials, 2006, 18, 2969-2973.	3.2	261
138	Enhancement of Electrical Properties of Electrically Conductive Adhesives (ECAs) by Using Novel Aldehydes. IEEE Transactions on Components and Packaging Technologies, 2006, 29, 758-763.	1.4	27
139	Novel Nanotechnology for Environmentally Friendly Interconnect Materials in Microelectronic Packaging Applications. , 2006, , .		1
140	Novel curing agent for lead-free electronics: Amino acid. Journal of Polymer Science Part A, 2006, 44, 1020-1027.	2.5	52
141	Variable Frequency Microwave Synthesis of Silver Nanoparticles. Journal of Nanoparticle Research, 2006, 8, 117-124.	0.8	106
142	Enhancement of electrical properties of anisotropically conductive adhesive joints via low temperature sintering. Journal of Applied Polymer Science, 2006, 99, 1665-1673.	1.3	52
143	Electrical property improvement of electrically conductive adhesives through in-situ replacement by short-chain difunctional acids. IEEE Transactions on Components and Packaging Technologies, 2006, 29, 173-178.	1.4	37
144	A Novel Aluminum-Filled Composite Dielectric for Embedded Passive Applications. IEEE Transactions on Advanced Packaging, 2006, 29, 295-306.	1.7	66

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145	Influence of flux on wetting behavior of lead-free solder balls during the infrared-reflow process. Journal of Electronic Materials, 2005, 34, 994-1001.	1.0	22
146	Lead-free interconnect technique by using variable frequency microwave. Journal of Electronic Materials, 2005, 34, 1081-1088.	1.0	16
147	Monolayer-protected silver nano-particle-based anisotropic conductive adhesives: Enhancement of electrical and thermal properties. Journal of Electronic Materials, 2005, 34, 1573-1578.	1.0	58
148	Molecular dynamics study of nanosilver particles for low-temperature lead-free interconnect applications. Journal of Electronic Materials, 2005, 34, 40-45.	1.0	33
149	Conductivity enhancement of nano silver-filled conductive adhesives by particle surface functionalization. Journal of Electronic Materials, 2005, 34, 1432-1439.	1.0	114
150	Adherence of self-assembled monolayers on gold and their effects for high-performance anisotropic conductive adhesives. Journal of Electronic Materials, 2005, 34, 266-271.	1.0	63
151	Thermal behavior of silver nanoparticles for low-temperature interconnect applications. Journal of Electronic Materials, 2005, 34, 168-175.	1.0	344
152	Reliability improvement of conductive adhesives on tin (Sn) surfaces. Journal of Adhesion Science and Technology, 2005, 19, 1427-1444.	1.4	14
153	MATERIALS SCIENCE: Electronics Without Lead. Science, 2005, 308, 1419-1420.	6.0	451
154	Molecular dynamics study on the coalescence of Cu nanoparticles and their deposition on the Cu substrate. Journal of Electronic Materials, 2004, 33, 1326-1330.	1.0	34
155	Stabilizing contact resistance of isotropically conductive adhesives on various metal surfaces by incorporating sacrificial anode materials. Journal of Electronic Materials, 2004, 33, 1381-1388.	1.0	19
156	A novel approach to stabilize contact resistance of electrically conductive adhesives on lead-free alloy surfaces. Journal of Electronic Materials, 2004, 33, 106-113.	1.0	33
157	Glass transition and relaxation behavior of epoxy nanocomposites. Journal of Polymer Science, Part B: Polymer Physics, 2004, 42, 3849-3858.	2.4	318
158	Improved stability of contact resistance of low melting point alloy incorporated isotropically conductive adhesives. IEEE Transactions on Components and Packaging Technologies, 2003, 26, 375-381.	1.4	22
159	The study of self-alignment capability of electrically conductive adhesives (ECAs) using low melting point alloy for flip-chip application. , 0, , .		0
160	The effect of toughening of no-flow underfill on fillet cracking of flip-chip device. , 0, , .		0
161	Study on the effect of toughening of no-flow underfill on fillet cracking. , 0, , .		1
162	The depletion/wetting of the low melting point alloy in electrically conductive adhesives (ECAs). , 0, , .		1

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163	Study on self-alignment capability of electrically conductive adhesives (ECAs) for flip-chip application. , 0, , .		3
164	Self-alignment feasibility study and contact resistance improvement of electrically conductive adhesives (ECAs). , 0, , .		1
165	Dielectric properties of polymer composite as integral capacitor. , 0, , .		1
166	Study of dielectric properties of polymer composite as integral capacitor. , 0, , .		0
167	Effect of sacrificial anodic fillers on contact resistance stability of electrically conductive adhesives onto lead-free alloy surfaces. , 0, , .		1
168	A novel technique for lead-free soldering process using variable frequency microwave (VFM). , 0, , .		2
169	Lead-free solder interconnect by variable frequency microwave (VFM). , 0, , .		2
170	Wafer bonding using microwave heating of parylene for MEMS packaging. , 0, , .		10
171	Formation of self assembled monolayer (SAM) on metal surfaces for high performance anisotropically conductive adhesives. , 0, , .		4
172	Reliability enhancement of electrically conductive adhesives in thermal shock environment [electronics packaging]. , 0, , .		0
173	Nano metal particles for low temperature interconnect technology. , 0, , .		5
174	Development of isotropic conductive adhesives with improved conductivity. , 0, , .		6
175	Physical properties and thermocycling performance of electrically conductive adhesives (ECAs) modified by flexible molecules. , 0, , .		1
176	Conductivity improvement of isotropically conductive adhesives. , 0, , .		3
177	Electrical property of conductive adhesives during temperature/humidity aging. , 0, , .		1
178	Molecular dynamics study on coalescence of silver (Ag) nanoparticles and their deposition on gold (Au) substrates. , 0, , .		1
179	Conductivity improvement of isotropic conductive adhesives with short-chain dicarboxylic acids. , 0, , .		11
180	High performance electrically conductive adhesives (ECAs) modified with novel aldehydes. , 0, , .		2

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181	Molecular dynamics simulation of lead free solder for low temperature reflow applications. , 0, , .		1
182	Development of conductive adhesives with novel corrosion inhibitors for stabilizing contact resistance on non-noble lead-free finishes. , 0, , .		0
183	Stabilizing contact resistance of conductive adhesives on Sn surface by novel corrosion inhibitors. , 0, , .		0
184	Improvement of electrical performance of anisotropically conductive adhesives. , 0, , .		5
185	The role of self-assembled monolayer (SAM) on Ag nanoparticles for conductive nanocomposite. , 0, , .		6
186	Synthesis of Ag-Cu alloy nanoparticles for lead-free interconnect materials. , 0, , .		17
187	Dielectric loss control of high-K polymer composites by coulomb blockade effects of metal nanoparticles for embedded capacitor applications. , 0, , .		3
188	Novel All Organic High Dielectric Constant Polyaniline/epoxy Composites for Embedded Capacitor Applications. , 0, , .		1
189	Effect of Ferritic Density and Zinc on Magnetic Properties of Cobalt Ferrite Nanocomposites. , 0, , .		3
190	Development of Novel Silver Nanoparticles/Polymer Composites as High K Polymer Matrix by In-situ Photochemical Method. , 0, , .		2
191	Electrochemical migration control of silver-paste conductive adhesives. , 0, , .		0
192	Simulation study of nanoparticle melting behavior for lead free nano solder application. , 0, , .		0
193	In-situ Photochemical Synthesis of Novel Silver Nanoparticles/Polymer Composites as High K Polymer Matrix for Embedded Passives Applications. , 0, , .		2
194	Large-Area Processable High k Nanocomposite-Based Embedded Capacitors. , 0, , .		3
195	In-situ Photochemical Synthesis of Novel Silver Nanoparticles-Polymer Composites as High K Polymer Matrix for Embedded Passives Applications. , 0, , .		0
196	A Novel Environmentally Friendly and Biocompatible Curing Agent for Lead-free Electronics. , 0, , .		1
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